



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.

2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

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TITLE: 256 I/O PBGA 23 X 23, 1.27 MM PITCH	DOCUMENT NO: 98ASA99291D	REV: A	
	CASE NUMBER: 1130B-01	25 APR 2005	
	STANDARD: JEDEC MS-034 BAJ-1		